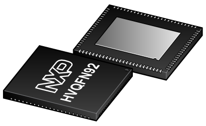


SOT2103-1

HVQFN92, thermal enhanced very thin quad flat package, no leads, 92 terminals, 0.5 mm pitch, 9.5 mm x 11 mm x 0.85 mm body

26 March 2020 **Package information**

1 Package summary

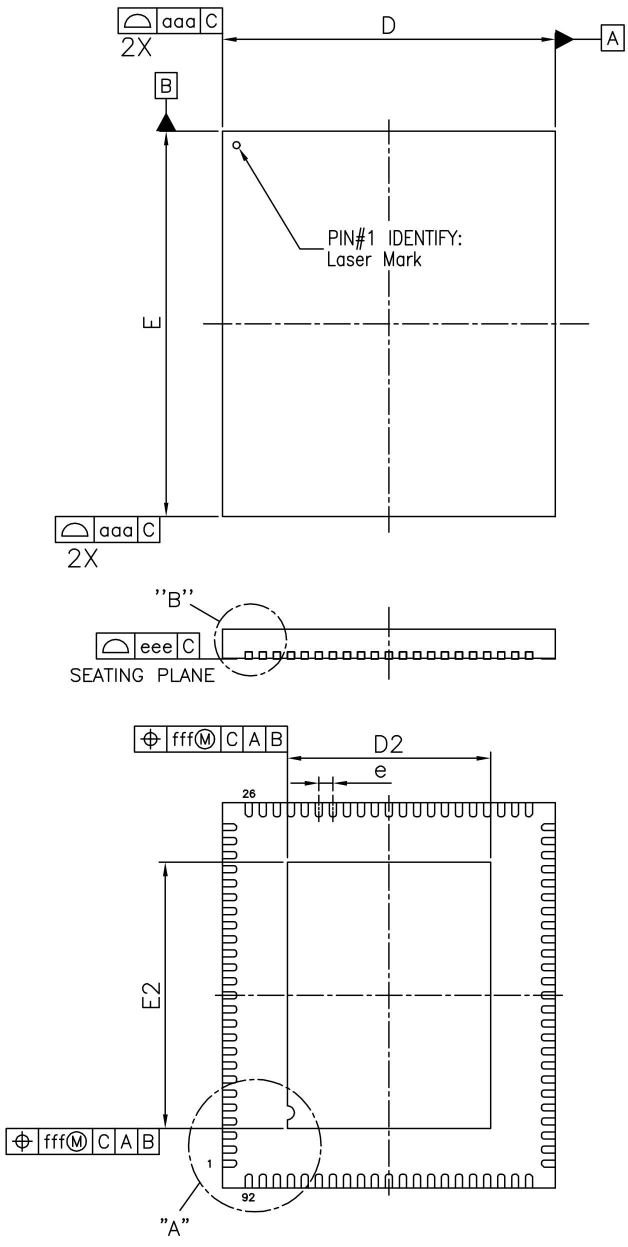
Terminal position code	Q (quad)
Package type descriptive code	HVQFN92
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	06-03-2012
Manufacturer package code	MV-A300830-00A

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	10.9	11	11.1	mm
package width	9.4	9.5	9.6	mm
package height	0.8	0.85	0.9	mm
nominal pitch	-	0.4	-	mm
actual quantity of termination	-	92	-	

2 Package outline

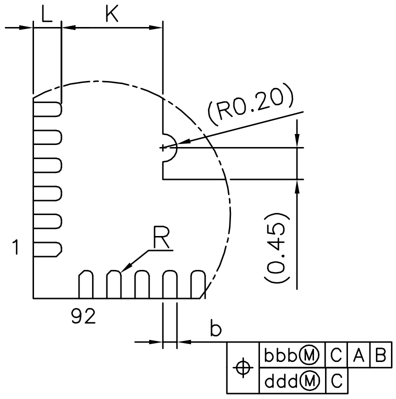
SOT2103-1



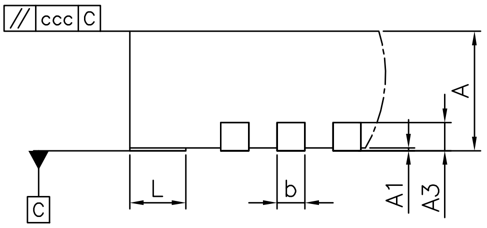
	STANDARD:	DRAWING NUMBER:	REVISION:	DATE:
MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	NON JEDEC	MV-A300830-00	-	03/06/12

Figure 1. Package outline HVQFN92 (SOT2103-1)

SOT2103−1



DETAIL : ”A”



DETAIL : ”B”

Symbol	Dimension in mm			Dimension in inch		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.80	0.85	0.90	0.031	0.033	0.035
A1	0.00	0.02	0.05	0.000	0.001	0.002
A3	0.20 REF			0.008 REF		
b	0.15	0.20	0.25	0.006	0.008	0.010
D	9.40	9.50	9.60	0.370	0.374	0.378
E	10.90	11.00	11.10	0.429	0.433	0.437
D2	5.70	5.80	5.90	0.224	0.228	0.232
E2	7.50	7.60	7.70	0.295	0.299	0.303
e	0.40 BSC			0.016 BSC		
L	0.30	0.40	0.50	0.012	0.016	0.020
K	0.20	−−−	−−−	0.008	−−−	−−−
R	0.075	−−−	−−−	0.003	−−−	−−−
aaa	0.10			0.004		
bbb	0.07			0.003		
ccc	0.10			0.004		
ddd	0.05			0.002		
eee	0.08			0.003		
fff	0.10			0.004		

NOTE:

1. CONTROLLING DIMENSION : MILLIMETER
2. REFERENCE DOCUMENT: JEDEC MO−220.

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: MV−A300830−00	REVISION: −	DATE: 03/06/12

Figure 2. Package outline detail HVQFN92 (SOT2103-1)

3 Legal information

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HVQFN92, thermal enhanced very thin quad flat package, no leads, 92 terminals, 0.5 mm pitch, 9.5 mm x 11 mm x 0.85 mm body

Contents

For more information, please visit: http://www.nxp.com
For sales office addresses, please send an email to: salesaddresses@nxp.com

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